

CUSTOMER:	DATI	3.

## APPROVAL SPECIFICATION

ROHS

PRODUCT NAME:	SMD power inductor
YOUR PART NO.:	
OUR PART NO.:	MPIM252010HE series
VERSION: V1.0	

RECEPTION				
THE SPECIFICAT	TION HAS BEEN ACCEP	TED.		
COMPANY:	DATE	:		
GIND DOWN				
CFMD	CHKD	RCVD		

### MANUFACTURING NAME

SHENZHEN MICROGATE TECHNOLOGY CO., LTD

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CFMD.	CHKD.	DSGD.
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### **Reference Only**

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### **Component SPEC Version Record**

Rev.	Effective Date	Changed Contents	Change Reasons	Approved By
1.0	May.18.2016	New released	/	Charles





### 1. Scope

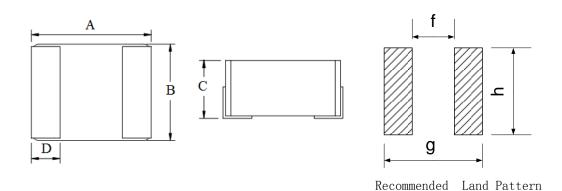
This specification applies to the MPIM252010HE series of SMD power inductor.

#### 2. Product Identification

 $\begin{array}{c|cccc} \underline{MPIM} & \underline{252010} & \underline{HE} & \underline{1R0} & \underline{M} & -\underline{LF} \\ \hline \textcircled{1} & \textcircled{2} & \textcircled{3} & \textcircled{4} & \textcircled{5} & \textcircled{6} \end{array}$ 

- Product Symbol
- 2 Product dimensions
- ③ Special process code
- 4 Inductance Value (R47:0.47 uH; 1R0: 1.0uH)
- 5 Induc tance Tolerance (M: ±20%; N: ±30%)
- 6 Lead free product.

#### 3. Appearance and Dimensions



Dimensions in mm						
A	A B C D f g h					
2.50±0.20	2.00±0.20	1.00Max.	0.60±0.20	1.20 Typ.	2.80 Typ.	2.00 Typ.

### 4. Testing Conditions

Unless otherwise specified, the standard conditions for measurement/test as:

Ambient Temperature : 5 to 35℃ Relative Humidity: 25 to 85% RH Atmospheric Pressure: 86 to 106 kPa

If any doubt on the results, measurements/tests should be made within the following limits:

Ambient Temperature :  $25\pm1$  °C Relative Humidity: 60 to 70% RH Atmospheric Pressure: 86 to 106 kPa

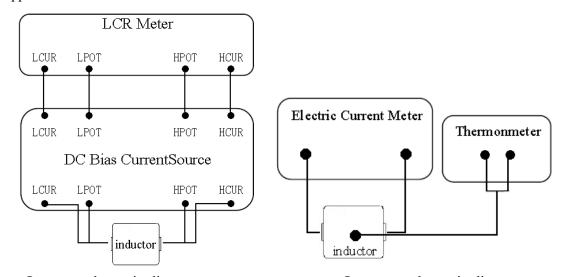


#### **5. Electrical Characteristics And Test Instruments**

Microgate Part No.	Inductance DCR(Ω)		Isat (A)		Irms (A)		
Wilchogate 1 art No.	L0 (uH) 1MHz &1V	Max.	Тур.	Max.	Тур.	Max.	Тур.
MPIM252010HER22M-LF	0.22±20%	0.014	0.013	7.20	7.60	5.10	5.50
MPIM252010HER33M-LF	033±20%	0.020	0.017	6.20	6.70	4.40	4.70
MPIM252010HER47M-LF	0.47 ±20%	0.028	0.025	5.50	6.00	3.90	4.20
MPIM252010HER68M-LF	0.68±20%	0.046	0.042	4.50	4.90	3.10	3.40
MPIM252010HE1R0M-LF	1.0±20%	0.054	0.048	4.30	4.70	2.70	3.00
MPIM252010HE1R5M-LF	1.5±20%	0.082	0.075	3.40	3.70	2.10	2.40
MPIM252010HE2R2M-LF	2.2±20%	0.115	0.107	2.70	3.00	1.70	2.00

#### Test instruments and remarks

- \* L test by CHROMA 3302 meter or equivalent.
- \* DCR test by Tonghui TH2516B meter or equivalent.
- \* CHROMA 3302 and 1320 meter for IDC.
- \* Rated current: Isat or Irms, whichever is smaller:
  - Isat: DC current (A) that will cause L0 to drop approximately 30%.
  - Irms: DC current (A) that will cause an approximate  $\Delta T$  of  $40^{\circ}$ C.
- \* Maximum rated voltage: DC 20 V.
- \* The part temperature (ambient + temp rise) should not exceed 125°C under worse case operating conditions. Circuit design, component placement, PCB trace size and thickness, airflow and other cooling provision all affect the part temperature. Part temperature should be verified in the end application.



Isat test schematic diagram

Irms test schematic diagram

#### 6. Condition of work

Operating temperature range:  $-55^{\circ}$ C ~  $+125^{\circ}$ C (Including self-heating).

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### 7. Reliability

No.	Item	Requirements	Test Methods and Remarks	Reference	Sample Size
1	Solderability	<ul><li>(1) No case deformation or change in appearance.</li><li>(2) Terminal area must have 95% min. solder coverage.</li></ul>	①Temperature:255±5°C, flux 5-10 s. ②Sample immersion tin furnace 5 ±0.5s. ③Immersed and in and out of speed: 25 ±6mm/s.	AEC-Q200 (J-STD-002)	15
2	Resistance to Soldering Heat		①The peak temperature: 260+5/-0°C. ②Reflow:3times. ③Temperature curve is as below:  Peak 265°C  Max. Ramp Up Rate-3°C/s  Max. Ramp Down Rate=-6°C/s  217°C  Time 25°C to Peak =8 min  Time	AEC-Q200 (MIL-STD-20 2 Method 210)	30
3	High Temperature Storage	(1) No case deformation or change in	①Temperature: 125±2°C. ②Time: 1000 hours. ③Measurement at 24±4 hours after test conclusion.  Temp High temperature 125°C Room Temp.  0 1000H Time	AEC-Q200 (MIL-STD -202 Method 108)	77
4	Low Temperature Storage	appearance. (2)   ΔL0/L0   ≤10%	①Temperature: -55±2°C. ②Time: 1000 hours. ③Measurement at 24±4 hours after test conclusion.  Room Temp.  1000H  Time  -55°C Low temperature 24H  Temp.	JESD22-A119	77
5	Thermal shock		①First -40°C for 15 minutes, last 125°C 15minutes as 1 cycle. Go through 300 cycles. ②Max transfer time is 20 second. ③Measurement at 24±4 hours after test conclusion.  125°C 15 min. 15 min.  Ambient 15 min. 20 s (max.)	MIL-STD -202 Method 107	30

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No.	Item	Requirements	Test Methods and Remarks	Reference	Sample Size
6	Humidity Resistance		①1000 hours, 85 °C/85%RH. ②Unpowered. ③Measurement at 24±4 hours after test conclusion.  High temperature High humidity  Room Temp 0 1000H Time	AEC-Q200 (MIL-STD -202 Method 103)	77
7	Terminal Strength		①The test samples shall be soldered to the board. ②17.64N, 60s,X,Ydirect.  Radius 1.5mm  DUT  Substrate  Press tools  Shear force	AEC-Q200 (AEC-Q200-0 06)	30
8	Board Flex	<ul> <li>(1) No case deformation or change in appearance.</li> <li>(2)   ΔL0/L0   ≤10%</li> </ul>	①Part mounted on a 100mm*40mm FR4 PCB board, which is 1.6±0.2 mm thick and as a Layer-thickness 35 µm ± 10 µm. ②Bending speed is 1mm/s. ③Keeping the P.C Board 2 mm minimum for 60 seconds.  Support Solder Chip Printed circuit board before testing  Printed circuit board under test Unit: mm  Displacement Unit: mm	AEC-Q200 (AEC-Q200-0 05)	30
9	Drop		①Height: 1 m, Free fall, 10times. ②Direction: 1 Angle, 1side, 2surface.	JESD22-B111	30
10	Vibration		①Frequency range: 10~2000Hz. ②Amplitude: 1.5mm or 20 G. ③Sweep time and duration: 10~2000~10Hz for 20 minutes. ④Each four hours(12 times) in X,Y,Z direction, 12 hours in total.	AEC-Q200 (MIL-STD-20 2 Method 204)	30

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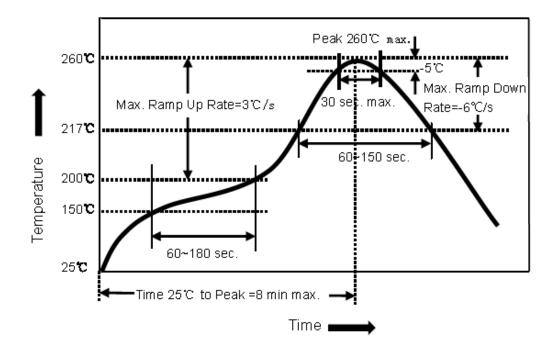


No.	Item	Requirements	Test Methods and Remarks	Reference	Sample Size
11	Loading at High Temperature	<ul> <li>(1) No case deformation or change in appearance.</li> <li>(2)   ΔL0/L0   ≤10%</li> </ul>	①Temperature: 85 ±2 °C. ②Time: 1000 hours. ③Applied Current: Rated current. ④Measurement at 24 ±4 hours after test conclusion.	AEC-Q200 (MIL-PRF-27)	77

<sup>\*</sup>All above experiments items need 3 Lot., sample size is as specified in the table above.

### 8. Recommended Soldering Conditions

#### (1) Reflow soldering conditions



<sup>\*</sup>Above reflow soldering curve is from J-STD-020D.

#### (2) Iron soldering

The following conditions must be strictly followed when using a soldering iron.

Pre-heating	150°C 1 minute	
Tip temperature	350℃ max	
Soldering iron output	30w max	
End of soldering iron	Ф1mm max	
Soldering time	3 seconds max	

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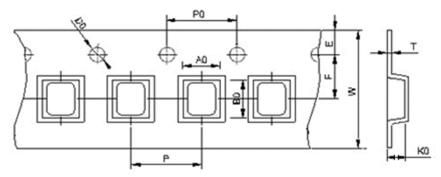
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<sup>\*</sup>Sample size standard is from AEC-Q200 : qualification sample size requirements.

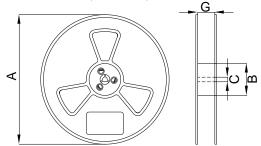
### 9. Package Information

#### (1) Dimension of tape (Unit: mm)



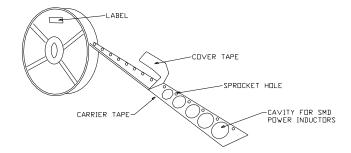
W	A0	В0	K0	Е	F	P	P0	D0	T
8.0±0.3	2.40±0.10	2.80±0.10	1.20±0.1	1.75±0.1	3.5±0.05	4.0±0.1	4.0±0.1	1.5+0.1/-0.0	0.18±0.03

#### (2) Dimension of reel (Unit: mm)



Symbol	Dimension
A	178±2
В	58±2
С	13.5±0.2
G	9.0±1.5

#### (3) Taping figure and drawing direction

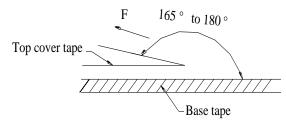


(4) Packaging quantities: 2000PCS/Reel.

### (5) Peeling strength of cover tape:

The peel force of top cover tape shall be between 0.10N to 1.0N

\*the peel force standard is from EIA-481-D



Room Temp.	Room Humidity	Room aim	Peel Speed
(°C)	(%)	(hpa)	mm/min
5-35	45-85	860-1060	300

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### 10. Products Storage

(1) Storage period

Products which inspected in MICROGATE over 12 months ago should be examined and used, which can be confirmed with inspection No. marked on the container. Solderability should be checked if this period is exceeded.

(2) Storage conditions

Products should be storage in the warehouse on the following conditions:

Temperature: -10 ~+ 35 °C

Humidity : Less than 70% relative and humidity No rapid change on temperature and humidity.

- (3) Don't keep products in corrosive gases such as sulfur, chlorine gas or acid, or it may cause oxidization of electrode, resulting in poor solderability.
- (4) Products should be storage on the palette for the prevention of the influence from humidity, dust and so on.
- (5) Products should be storage in the warehouse without heat shock, vibration, direct sunlight and so on.
- (6) Products should be storage under the airtight packaged condition.

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